IoT Sensing SDK
Getting started with IoT Sensing SDK (ISSDK) v1.7 middleware
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1 Prerequisites

This document assumes completion of the following prerequisites prior to attempting to use the ISSDK v1.7 middleware:

- One of the recommended IDEs is installed on the development PC (see the release notes)
- A FRDM-K64F-AGM01 sensor kit is connected to the development PC
- User understanding of the debug environment set up for the Freedom family of development boards using OpenSDA or third-party debugger with their IDE of choice
- User familiarity with the MCUXpresso SDK and MCUXpresso SDK Builder

2 Overview

The IoT Sensing Software Development Kit (ISSDK) is the embedded software framework enabling NXP’s digital and analog sensors platforms for IoT applications. ISSDK provides a unified set of sensor support models that target NXP’s portfolio of sensors across a broad range of ARM Cortex core-based Microcontrollers. ISSDK is offered as a middleware component in MCUXpresso SDK for supported microcontrollers. ISSDK relies on the SDK 2.x drivers and project release infrastructure to create a unified user experience. ISSDK v1.7 combines a set of robust sensor drivers and algorithms along with example applications to allow a user to get started using NXP sensors quickly.

For more information on ISSDK, go to [www.nxp.com/iotsensingsdk](http://www.nxp.com/iotsensingsdk).

2.1 ISSDK architecture

Figure 1 shows the high-level layer cake architecture of the ISSDK v1.7 middleware. ISSDK is designed to provide separable layers of functionality that a customer can choose to use or ignore based on their specific needs. In addition, the ISSDK architecture is portable due to the use of open APIs (ARM Ltd. CMSIS Driver APIs). ISSDK is designed to allow users to start with as small a production footprint (memory and CPU load) as is practical for their particular application. This is typically done by selecting the Bare Metal option; however, some applications may prefer using one of the RTOSs supplied with MCUXpresso SDK 2.4.

![ISSDK Architecture Diagram](image-url)
In the following sections, this guide focuses on how ISSDK can be deployed via
MCUXpresso for a specific Freedom Sensor Toolbox sensor demonstration kit called
the FRDM-K64F-AGM01. This kit combines the Kinetis FRDM-K64F development board
with a FRDM-STBC-AGM01 sensor shield to provide a stand-alone, low cost sensor
development platform.

3 NXP Freedom Sensor Toolbox Sensor Development Ecosystem

NXP provides a sensor development ecosystem called the Freedom Sensor Toolbox.
This ecosystem is designed to provide solutions for hardware and software that enable
customers to evaluate and prototype with sensors quickly and easily. ISSDK v1.7 is
deployed on top of the Freedom Sensor Toolbox hardware platforms and is expected to
become the embedded software support platform for the ecosystem.

The following figure shows how the Freedom Sensor Toolbox development hardware
can be used to explore the ISSDK v1.7 software. In this example, the MCUXpresso IDE
is used to compile, load and launch an existing project into the FRDM-K64F-AGM01 kit.
The customer may then launch a terminal emulator to examine the debug console output
provided for many ISSDK v1.7 projects.

Figure 2. Freedom Sensor Toolbox development environment

More information about the Freedom Sensor Toolbox development ecosystem can
be found at http://nxp.com/sensortoolbox. The remainder of this document focuses on
the steps involved to use the FRDM-K64F-AGM01 development kit with the ISSDK
enablement software.
ISSDK v1.7 is fully integrated into the MCUXpresso Web and SDK Builder delivery system. MCUXpresso includes both cloud and locally based tools to collect and build projects from the MCUXpresso SDK repositories. MCUXpresso SDK 2.x is built using a hierarchy of deployed Git repositories. Specific project codebases are built through the online tool. A given codebase is specified by its target (device, board, or kit desired), the version of MCUXpresso SDK 2.x, the supported IDEs (MCUXpresso IDE, IAR, Keil, GCC), and the target Host OS (Windows, Mac, or Linux).

4.1 MCUXpresso Web & SDK Builder

MCUXpresso Web & SDK Builder is a cloud-based system used to build MCUXpresso SDK 2.x packages. ISSDK is an optional component that can be deployed by MCUXpresso in two ways:

- If the customer selects a FRDM sensor kit, such as the FRDM-K64F-AGM01, then the ISSDK sensor drivers and example applications appropriate for that kit are deployed into the package.
- If the customer selects a supported device or FRDM board and checks the box for optional ISSDK support, then all the sensor drivers and example applications are deployed into the package.

It should be noted that in both cases the MCUXpresso SDK 2.x drivers and example applications are also deployed alongside the ISSDK files.

Figure 3. shows the MCUXpresso environment for deploying ISSDK (see https://mcuxpresso.nxp.com/en/configuration-settings). In this example, the customer has selected the FRDM-K64F-AGM01 kit, the MCUXpresso IDE, and Windows host operating system. Notice that ISSDK middleware component has been selected by default because the target is a board/shield kit. When the customer selects the Build SDK Package, the request is sent to the build servers. Requests for packages are served in order and when the package is ready, a notification is returned to the customer. At this point, the customer may download the package (a zip file) and deploy it into their local system.
4.2 Deployment directory structure

Once the MCUXpresso package has been downloaded, the user can extract the package on their local machine. Figure 4 displays the MCUXpresso directory structure.

The CMSIS, devices, docs, RTOS, and tools directories are unchanged from standard MCUXpresso SDK 2.x deployments. ISSDK v1.7 projects appear as new targets in the boards directory. Figure 5 illustrates the directory where frdmk64f_agm01 (ISSDK) reference example projects are available, as well as the base projects for the frdmk64f.

In addition, a new middleware component is created that contains the ISSDK drivers, algorithms and other support files as shown in Figure 6.

5 Build and run a sensor driver example

Choose FRDM-K64F-AGM01 kit configuration and download SDK package from MCUXpresso SDK Builder. Figure 7 and Figure 8 illustrate how to get the FRDM-K64F-AGM01 SDK package from MCUXpresso configuration.
Install downloaded SDK package into MCUXpresso IDE (drag and drop SDK package into “Installed SDKs” view). Start SDK import wizard, import any existing ISSDK example by choosing frdmk64_agm01 board for your project, build the imported project and load the image to FRDM-K64FAGM01 kit. This creates a standalone project in your workspace. Refer to Figure 8.
Figure 8. Creating a standalone project in the workspace

Notice that the code is ready to start in the file `fxos8700_interrupt.c`, which is the main application for this example.
Start the program execution. The blue LED begins to flash on the FRDM-K64F board. Next, start a terminal emulation program with the serial port set as shown in Figure 9.

![Figure 9. Terminal emulation program with serial port set](image)

In this example, each data ready interrupt from the FXOS8700 triggers the application to read the raw X-, Y-, Z-axis accelerometer values. These raw values are then converted to 16-bit unsigned integers and output in real time to the debug console.

6 Build and run sensor fusion

Start SDK import wizard and import ISSDK sensor fusion example by choosing frdmk64_agm01 board for your project. This creates a standalone project in your workspace. Refer to Figure 11.

![Figure 10. Debug console output](image)
Build the sensor fusion project in the MCUXpresso IDE and load the image to FRDM-K64F-AGM01 kit. Refer to Figure 12.
Notice the code is ready to start in the file `main_agm01_freertos_two_tasks.c`, which is the main application for this example.

Start the program execution. The green LED begins to flash on the FRDM-K64F board.

You can now install the Sensor Fusion GUI application in order to visualize the operation of the Sensor Fusion application. Go to [http://nxp.com/sensorfusion](http://nxp.com/sensorfusion), download the latest Sensor Fusion for Windows GUI and install it. Launch the Sensor Fusion GUI. Select the Port from the pull-down menu. The GUI main screen should resemble [Figure 13](#).

![Sensor Fusion GUI](image)

**Figure 13. Sensor Fusion GUI**

This completes the exercise to run the ISSDK 1.7 Sensor Fusion project.
# Revision history

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